

*Sub A1 B1
cancel*

a solder bump interposed between the printed circuit board and the electronic component so as to fix the electronic component to the printed circuit board; and

an insulated film disposed between the printed circuit board and the electronic component so as to define a through hole for receiving the solder bump, wherein

the through hole is designed to form a constriction in the solder bump between the printed circuit board and the electronic component.

X2

3. (Amended) The printed circuit board unit according to claim 1 [2], wherein the insulated film is superposed on the printed circuit board so as to form the constriction right on a conductive pad on the printed circuit board.